

MULTILAYER CERAMIC SUBSTRATE WITH SINGLE VIA ANCHORED PAD AND METHOD OF FORMING

Abstract

A multilayer ceramic substrate in which an outer metal pad is anchored to the substrate by a single metal-filled via in the first ceramic layer adjacent to the metal pad. In turn, this single metal-filled via is anchored to the substrate by a larger, single metal-filled via in the next ceramic layer adjacent to the first ceramic layer. Preferably, the metal-filled vias and metal pad are 100 volume percent metal.